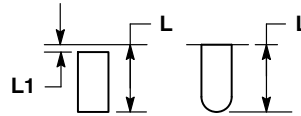
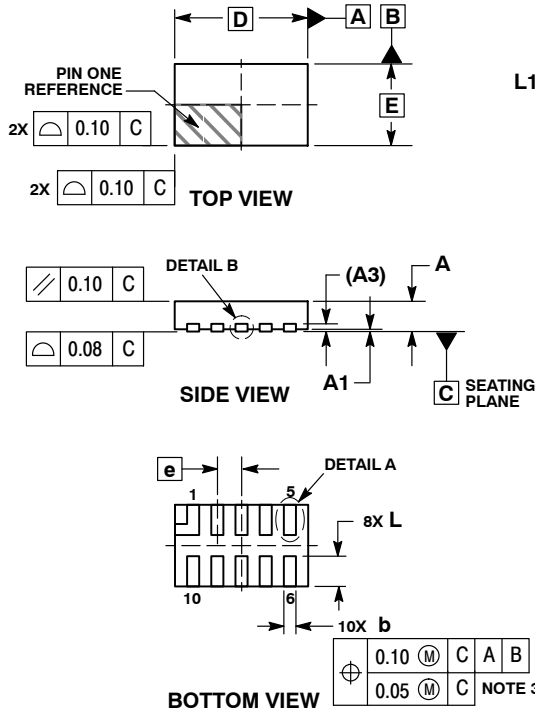




SCALE 4:1

XDFN10 2.2x1.35, 0.4P
CASE 711AU
ISSUE B

DATE 17 JUN 2014


DETAIL A
ALTERNATE
CONSTRUCTIONS

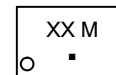
EXPOSED Cu MOLD CMPD


DETAIL B
ALTERNATE
CONSTRUCTION

NOTES:

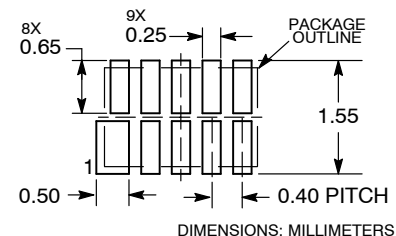
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	2.20 BSC	
E	1.35 BSC	
e	0.40 BSC	
L	0.40	0.60
L1	---	0.15

**GENERIC
MARKING DIAGRAM***


- XX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED
MOUNTING FOOTPRINT**


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